

Fairchild Semiconductor Product Package Material Disclosure

| Package Type | TSSOP-28 | | | | | |
|---------------------------|---------------------------------|-----------------|--------------------------|-----------------------------|-----------------------------|------------|
| Weight of Package (grams) | Maximum | 1.21E-01 | | | | |
| | Minimum | 1.14E-01 | | | | |
| Component | Material | Weight in grams | Substance in material | Wt% in finished product min | Wt% in finished product max | CAS # |
| Lead Frame | Copper alloy | 4.61E-02 | Copper | 37.99 | 40.34 | |
| | | | Nickel | 36.54 | 38.60 | 7440-50-8 |
| | | | Silicon | 1.14 | 1.21 | 7440-02-0 |
| | | | Magnesium | 0.25 | 0.26 | 7440-21-3 |
| | | | Silver (DP) | 0.06 | 0.06 | 7439-95-4 |
| | | | | 0.00 | 0.20 | 7440-22-4 |
| Encapsulation | Epoxy | 6.02E-02 | Silica | 49.60 | 52.67 | |
| | | | Carbon Black | 30.68 | 40.91 | |
| | | | Resin | 0.00 | 0.77 | |
| | | | Antimony Compound | 7.67 | 17.64 | 1309-64-4 |
| | | | Brominated Compound | 0.26 | 1.53 | |
| | | | | 0.77 | 2.05 | 68541-56-0 |
| Plating | Solder | 5.83E-03 | Tin | 1.65 | 8.25 | |
| | | | Lead | 1.40 | 7.01 | 7440-31-5 |
| | or Lead-free Solder | 5.83E-03 | Tin | 0.25 | 1.24 | 7439-92-1 |
| Chip | Silicon and inorganic compounds | 3.98E-03 | | 1.65 | 8.25 | |
| | | | | 1.65 | 8.25 | 7440-31-5 |
| Die Attach | Adhesive | 4.31E-04 | Silicon and trace metals | 3.21 | 3.55 | 7440-21-3 |
| | | | Silver | 3.21 | 3.55 | |
| | | | Resin | | | |
| Wire Bond | Gold Wire | 1.19E-03 | | 0.35 | 0.38 | |
| | | | Gold | 0.26 | 0.29 | 7440-22-4 |
| | | | Resin | 0.09 | 0.10 | |
| | | | Gold | 0.96 | 1.06 | |
| | | | | 0.96 | 1.06 | 7440-57-5 |



Materials Disclosure Disclaimer

The information provided in this Materials Disclosure is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company. Also, there may not be information included in

